

Single 2-Input NOR Gate

MC74HC1G02

The MC74HC1G02 is a high speed CMOS 2-input NOR gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The MC74HC1G02 output drive current is 1/2 compared to MC74HC series.

Features

- High Speed: $t_{PD} = 7 \text{ ns}$ (Typ) at $V_{CC} = 5 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu\text{A}$ (Max) at $T_A = 25^\circ\text{C}$
- High Noise Immunity
- Balanced Propagation Delays ($t_{PLH} = t_{PHL}$)
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2 \text{ mA}$)
- Chip Complexity: < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

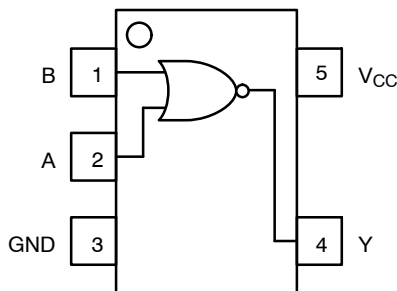


Figure 1. Pinout

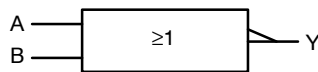
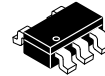


Figure 2. Logic Symbol

PIN ASSIGNMENT	
1	B
2	A
3	GND
4	Y
5	V_{CC}



SC-88A
DF SUFFIX
CASE 419A



TSOP-5
DT SUFFIX
CASE 483

XX = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.



SC-74A
DBV SUFFIX
CASE 318BQ

XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	L

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

MC74HC1G02

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage SC-88A (NLV), TSOP-5 SC-88A, SC-74A	-0.5 to +7.0 -0.5 to +6.5	V
V_{IN}	DC Input Voltage	-0.5 to $V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC Input Diode Current	± 20	mA
I_{OK}	DC Output Diode Current	± 20	mA
I_{OUT}	DC Output Source/Sink Current	± 12.5	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin	± 25	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 1) SC-88A SC-74A	377 320	°C/W
P_D	Power Dissipation in Still Air at 85°C SC-88A SC-74A	332 390	mW
MSL	Moisture Sensitivity	Level 1	
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage (Note 2) Human Body Model Charged Device Model	2000 1000	V
$I_{LATCHUP}$	Latchup Performance (Note 3) SC-88A (NLV), TSOP-5 SC-88A, SC-74A	± 500 ± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow per JESD51-7.
2. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued per JEDEC/JEP172A.
3. Tested to EIA/JESD78 Class II.

MC74HC1G02

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	DC Supply Voltage	2.0	6.0	V	
V _{IN}	DC Input Voltage	0.0	V _{CC}	V	
V _{OUT}	DC Output Voltage	0.0	V _{CC}	V	
T _A	Operating Temperature Range	−55	+125	°C	
t _r , t _f	Input Rise and Fall Time	SC-88A (NLV), TSOP-5		ns	
		V _{CC} = 2.0 V	0		1000
		V _{CC} = 3.0 V	0		600
		V _{CC} = 4.5 V	0		500
		V _{CC} = 6.0 V	0		400
	Input Rise and Fall Time	SC-88A, SC-74A		ns/V	
		V _{CC} = 2.0 V	0		20
		V _{CC} = 2.3 V to 2.7 V	0		20
		V _{CC} = 3.0 V to 3.6 V	0		10
		V _{CC} = 4.5 V to 6.0 V	0		5

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C} \leq T_A \leq 85^\circ\text{C}$		$-55^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	High-Level Input Voltage		2.0	1.5	–	–	1.5	–	1.5	–	V
			3.0	2.1	–	–	2.1	–	2.1	–	
			4.5	3.15	–	–	3.15	–	3.15	–	
			6.0	4.20	–	–	4.20	–	4.20	–	
V_{IL}	Low-Level Input Voltage		2.0	–	–	0.5	–	0.5	–	0.5	V
			3.0	–	–	0.9	–	0.9	–	0.9	
			4.5	–	–	1.35	–	1.35	–	1.35	
			6.0	–	–	1.80	–	1.80	–	1.80	
V_{OH}	High-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -20\text{ }\mu\text{A}$	2.0	1.9	2.0	–	1.9	–	1.9	–	V
			3.0	2.9	3.0	–	2.9	–	2.9	–	
			4.5	4.4	4.5	–	4.4	–	4.4	–	
			6.0	5.9	6.0	–	5.9	–	5.9	–	
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -2\text{ mA}$ $I_{OH} = -2.6\text{ mA}$	4.5	4.18	4.31	–	4.13	–	4.08	–	
			6.0	5.68	5.80	–	5.63	–	5.58	–	
V_{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 20\text{ }\mu\text{A}$	2.0	–	0.0	0.1	–	0.1	–	0.1	V
			3.0	–	0.0	0.1	–	0.1	–	0.1	
			4.5	–	0.0	0.1	–	0.1	–	0.1	
			6.0	–	0.0	0.1	–	0.1	–	0.1	
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 2\text{ mA}$ $I_{OL} = 2.6\text{ mA}$	4.5	–	0.17	0.26	–	0.33	–	0.40	
			6.0	–	0.18	0.26	–	0.33	–	0.40	
I_{IN}	Input Leakage Current	$V_{IN} = 6.0\text{ V}$ or GND	6.0	–	–	± 0.1	–	± 1.0	–	± 1.0	μA
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0	–	–	1.0	–	10	–	40	μA

MC74HC1G02

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	T _A = 25°C			–40°C ≤ T _A ≤ 85°C		–55°C ≤ T _A ≤ 125°C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, (A or B) to Y	V _{CC} = 5.0 V C _L = 15 pF	–	3.5	15	–	20	–	25	ns
		V _{CC} = 2.0 V C _L = 50 pF	–	20	100	–	125	–	155	
		V _{CC} = 3.0 V	–	11	27	–	35	–	90	
		V _{CC} = 4.5 V	–	8	20	–	25	–	35	
		V _{CC} = 6.0 V	–	7	17	–	21	–	26	
t _{TLH} , t _{THL}	Output Transition Time	V _{CC} = 5.0 V C _L = 15 pF	–	3	10	–	15	–	20	ns
		V _{CC} = 2.0 V C _L = 50 pF	–	25	125	–	155	–	200	
		V _{CC} = 3.0 V	–	16	35	–	45	–	60	
		V _{CC} = 4.5 V	–	11	25	–	31	–	38	
		V _{CC} = 6.0 V	–	9	21	–	26	–	32	
C _{IN}	Input Capacitance		–	5	10	–	10	–	10	pF
C _{PD}	Power Dissipation Capacitance (Note 4)	Typical @ 25°C, V _{CC} = 5.0 V								pF
		10								

4. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

MC74HC1G02



*C_L includes probe and jig capacitance
R_T is Z_{OUT} of pulse generator (typically 50 Ω)
f = 1 MHz

Figure 3. Test Circuit

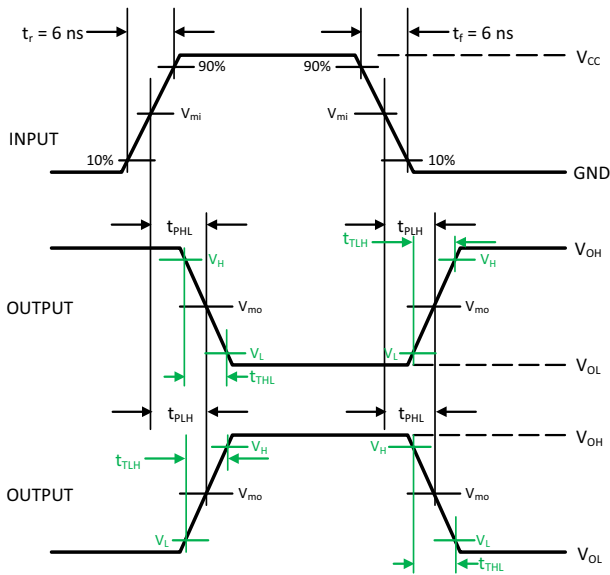


Figure 4. Switching Waveforms

V _{CC} , V	V _{mi} , V	V _{mo} , V		V _L , V	V _H , V	V _Y , V
		t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}			
3.0 to 3.6	V _{CC} /2	V _{CC} /2	V _{CC} /2	V _{OL} + 0.1 (V _{OH} - V _{OL})	V _{OL} + 0.9 (V _{OH} - V _{OL})	0.3
4.5 to 5.5	V _{CC} /2	V _{CC} /2	V _{CC} /2	V _{OL} + 0.1 (V _{OH} - V _{OL})	V _{OL} + 0.9 (V _{OH} - V _{OL})	0.3

5. t_{TLH} and t_{THL} are measured from 10% to 90% of (V_{OH} - V_{OL}), and 90% to 10% of (V_{OH} - V_{OL}), respectively.

MC74HC1G02

ORDERING INFORMATION

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping [†]
MC74HC1G02DFT2G	SC-88A	H3	Q4	3000 / Tape & Reel
NLVHC1G02DFT2G*	SC-88A	H3	Q4	3000 / Tape & Reel
MC74HC1G02DTT1G**	TSOP-5	H3	Q4	3000 / Tape & Reel
MC74HC1G02DBVT1G	SC-74A	H3	Q4	3000 / Tape & Reel

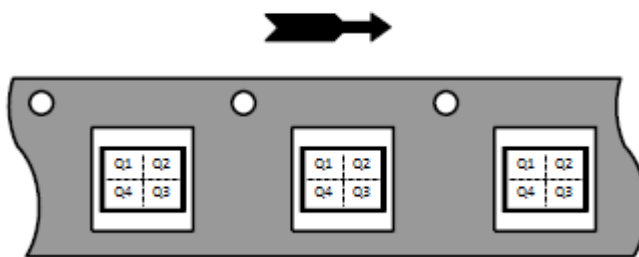
[†]For complete information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

**Please refer to NLV specifications for this device.

Pin 1 Orientation in Tape and Reel

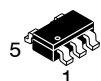
Direction of Feed



MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

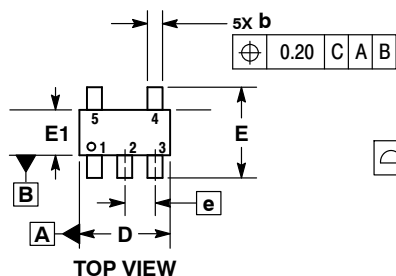
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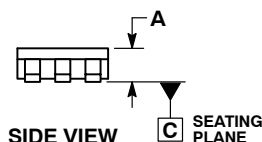
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SC-74A CASE 318BQ ISSUE B

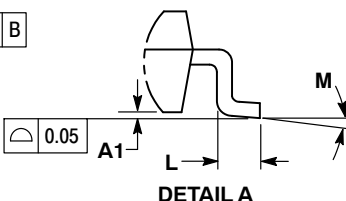
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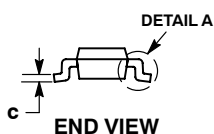
TOP VIEW



SIDE VIEW



DETAIL A



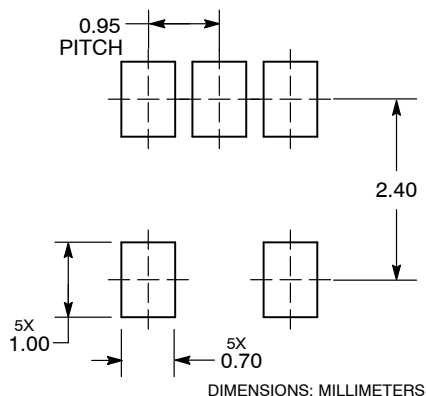
END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

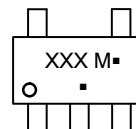
DIM	MILLIMETERS	
	MIN	MAX
A	0.90	1.10
A1	0.01	0.10
b	0.25	0.50
c	0.10	0.26
D	2.85	3.15
E	2.50	3.00
E1	1.35	1.65
e	0.95 BSC	
L	0.20	0.60
M	0°	10°

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER: 98AON66279G

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DESCRIPTION: SC-74A

PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

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SCALE 2:1

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE L

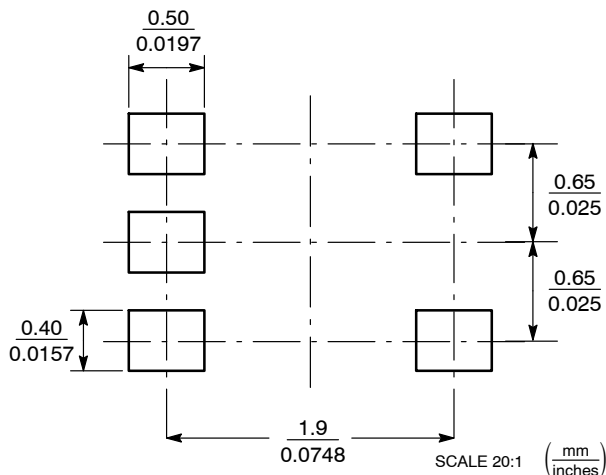
DATE 17 JAN 2013



D 5 PL $\oplus$ 0.2 (0.008) (M) B (M)



SOLDER FOOTPRINT

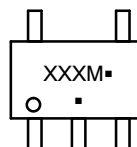


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 3:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6:
PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:	SC-88A (SC-70-5/SOT-353)	PAGE 1 OF 1

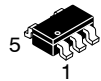
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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

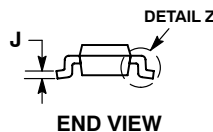
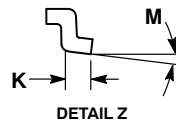
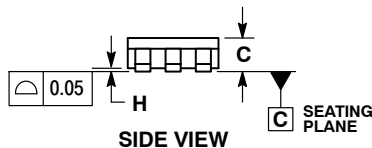
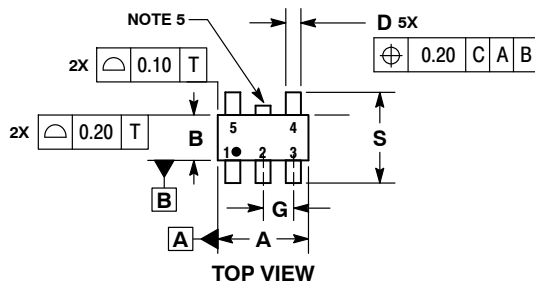
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SCALE 2:1

TSOP-5 CASE 483 ISSUE N

DATE 12 AUG 2020

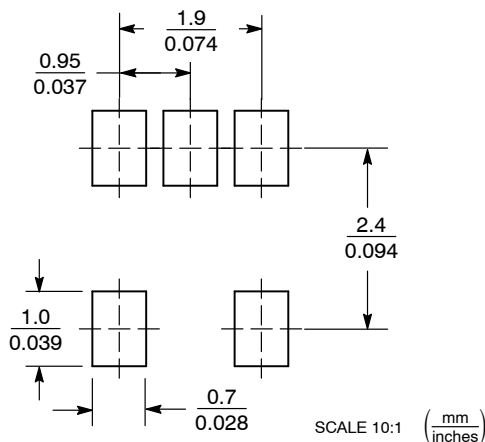


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

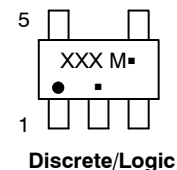
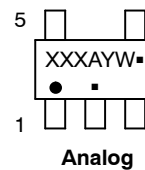
DIM	MILLIMETERS	
	MIN	MAX
A	2.85	3.15
B	1.35	1.65
C	0.90	1.10
D	0.25	0.50
G	0.95 BSC	
H	0.01	0.10
J	0.10	0.26
K	0.20	0.60
M	0°	10°
S	2.50	3.00

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ■ = Pb-Free Package

XXX = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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